Preferred Device

# **Silicon Controlled Rectifiers**

# **Reverse Blocking Thyristors**

Designed primarily for half-wave ac control applications, such as motor controls, heating controls and power supplies; or wherever half-wave silicon gate-controlled, solid-state devices are needed.

- Glass-Passivated Junctions
- Blocking Voltage to 400 Volts
- TO-220 Construction Low Thermal Resistance, High Heat Dissipation and Durability
- Device Marking: Logo, Device Type, e.g., MCR218-2, Date Code

### **MAXIMUM RATINGS** ( $T_J = 25^{\circ}C$ unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off–State Voltage(1)  (T <sub>J</sub> = -40 to 125°C, Gate Open)  MCR218-2  MCR218-4  MCR218-6	VDRM, VRRM	50 200 400	Volts
On-State RMS Current (180° Conduction Angles; T <sub>C</sub> = 70°C)	IT(RMS)	8.0	А
Peak Non-repetitive Surge Current (1/2 Cycle, Sine Wave 60 Hz, T <sub>J</sub> = 125°C)	ITSM	100	A
Circuit Fusing Considerations (t = 8.3 ms)	l <sup>2</sup> t	26	A <sup>2</sup> s
Forward Peak Gate Power (Pulse Width ≤ 1.0 μs, T <sub>C</sub> = 70°C)	Рдм	5.0	Watts
Forward Average Gate Power (t = 8.3 ms, T <sub>C</sub> = 70°C)	PG(AV)	0.5	Watts
Forward Peak Gate Current (Pulse Width ≤ 1.0 μs, T <sub>C</sub> = 70°C)	I <sub>GM</sub>	2.0	А
Operating Junction Temperature Range	TJ	-40 to +125	°C
Storage Temperature Range	T <sub>stg</sub>	-40 to +150	°C

(1) VDRM and VRRM for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

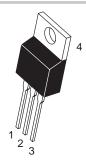


#### ON Semiconductor

http://onsemi.com

# SCRs 8 AMPERES RMS 50 thru 400 VOLTS





TO-220AB CASE 221A STYLE 3

PIN ASSIGNMENT		
1	Cathode	
2	Anode	
3	Gate	
4	Anode	

#### ORDERING INFORMATION

Device	Package	Shipping
MCR218-2	TO220AB	500/Box
MCR218-4	TO220AB	500/Box
MCR218-6	TO220AB	500/Box

**Preferred** devices are recommended choices for future use and best overall value.

#### THERMAL CHARACTERISTICS

Characteristic		Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	2.0	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds	TL	260	°C

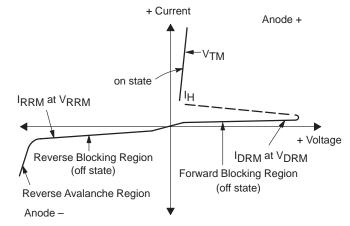
#### **ELECTRICAL CHARACTERISTICS** (T<sub>.1</sub> = 25°C unless otherwise noted.)

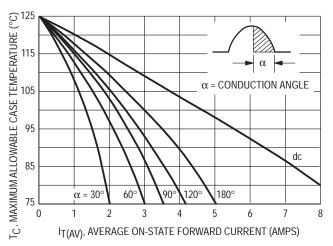
Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	•		•	•	•
Peak Repetitive Forward or Reverse Blocking Current ( $V_{AK}$ = Rated $V_{DRM}$ or $V_{RRM}$ , Gate Open) $T_{J}$ = 25°C $T_{J}$ = 125°C	I <sub>DRM</sub> , I <sub>RRM</sub>	_	_	10 2.0	μA mA
ON CHARACTERISTICS	-			•	
Peak Forward On-State Voltage(1) (I <sub>TM</sub> = 16 A Peak)	VTM	_	1.5	1.8	Volts
Gate Trigger Current (Continuous dc) (V <sub>D</sub> = 12 V, R <sub>L</sub> = 100 Ohms)	<sup>I</sup> GT	_	10	25	mA
Gate Trigger Voltage (Continuous dc) (V <sub>D</sub> = 12 V, R <sub>L</sub> = 100 Ohms)	VGT	_	_	1.5	Volts
Gate Non–Trigger Voltage (Rated 12 V, R <sub>L</sub> = 100 Ohms, T <sub>J</sub> = 125°C)	V <sub>GD</sub>	0.2	_	_	Volts
Holding Current (V <sub>D</sub> = 12 Vdc, Initiating Current = 200 mA, Gate Open)	lн	_	16	30	mA
DYNAMIC CHARACTERISTICS					
Critical Rate-of-Rise of Off-State Voltage (V <sub>D</sub> = Rated V <sub>DRM</sub> , Exponential Waveform, Gate Open, T <sub>J</sub> = 125°C)	dv/dt	_	100	_	V/μs

<sup>(1)</sup> Pulse Test: Pulse Width = 1.0 ms, Duty Cycle ≤ 2%.

### **Voltage Current Characteristic of SCR**

Symbol	Parameter
V <sub>DRM</sub>	Peak Repetitive Off State Forward Voltage
IDRM	Peak Forward Blocking Current
VRRM	Peak Repetitive Off State Reverse Voltage
I <sub>RRM</sub>	Peak Reverse Blocking Current
V <sub>TM</sub>	Peak On State Voltage
I <sub>H</sub>	Holding Current





15 α dc  $\alpha$  = Conduction Angle 180° 120° 60°  $\alpha = 30^{\circ}$ 1.0 3.0 2.0 4.0 5.0 6.0 7.0 8.0 I<sub>T(AV)</sub>, AVG. ON-STATE CURRENT (AMPS)

Figure 1. Current Derating

Figure 2. On-State Power Dissipation

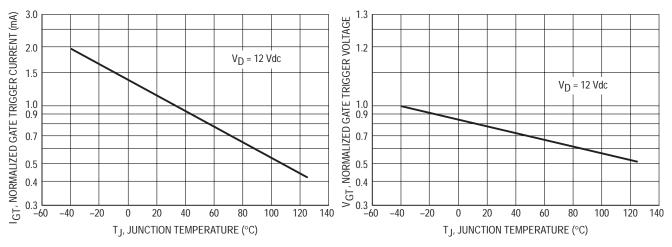


Figure 3. Typical Gate Trigger Current versus Temperature

Figure 4. Typical Gate Trigger Voltage versus Temperature

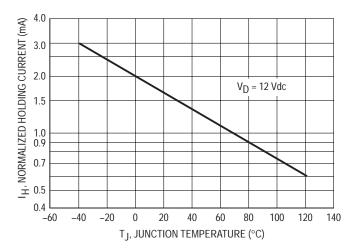
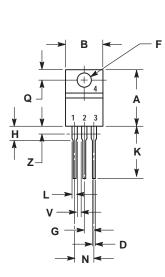
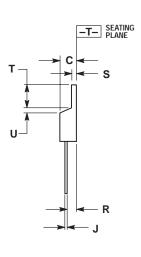


Figure 5. Typical Holding Current versus Temperature

#### **PACKAGE DIMENSIONS**

TO-220AB CASE 221A-07 ISSUE Z





- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.014	0.022	0.36	0.55
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045		1.15	
Z		0.080		2.04

- STYLE 3: PIN 1. CATHODE 2. ANODE

  - 3. GATE 4. ANODE

# **Notes**



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